

ABSTRACT**Single-strip moulding apparatus**

Electronic components, chips, are moulded in a single-strip moulding apparatus. The products to be moulded are placed in a mould consisting of two halves, one of the halves whereof displays recesses for receiving a component, which half is
5 connected via a channel with a cavity for receiving a quantity of moulding material.

After use the mould must be cleaned and the moulded product carried away. This is carried out by a cleaning-discharge unit combined into a unit.